

MOSFETs Silicon P-Channel MOS (U-MOSVI)

# SSM3J371R

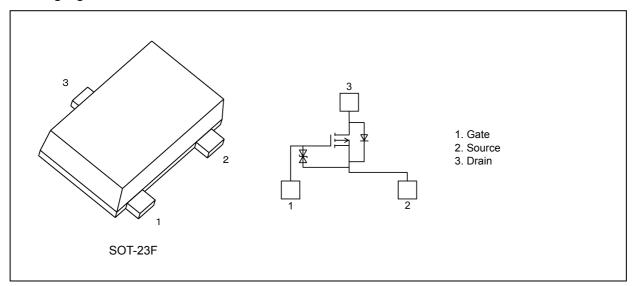
#### 1. Applications

· Power Management Switches

#### 2. Features

- (1) AEC-Q101 qualified (Please see the orderable part number list)
- (2) 1.5-V gate drive voltage.
- (3) Low drain-source on-resistance
  - $: R_{DS(ON)} = 150 \text{ m}\Omega \text{ (max) } (@V_{GS} = -1.5 \text{ V})$
  - $R_{DS(ON)} = 100 \text{ m}\Omega \text{ (max) (@V_{GS} = -1.8 V)}$
  - $R_{\rm DS(ON)} = 75 \ {\rm m}\Omega \ ({\rm max}) \ (@V_{\rm GS} = -2.5 \ {\rm V})$
  - $R_{\mathrm{DS(ON)}} = 55 \ \mathrm{m}\Omega \ (\mathrm{max}) \ (@V_{\mathrm{GS}} = -4.5 \ \mathrm{V})$

#### 3. Packaging and Internal Circuit



#### 4. Orderable part number

Orderable part number	AEC-Q101		Note			
SSM3J371R,LF			General Use			
SSM3J371R,LXGF	YES	(Note 1)	Unintended Use	(Note 1)		
SSM3J371R,LXHF	YES		Automotive Use			

Note 1: For more information, please contact our sales or use the inquiry form on our website.

Start of commercial production



#### 5. Absolute Maximum Ratings (Note) (Unless otherwise specified, Ta = 25°C)

Characteristics				Rating	Unit
Drain-source voltage			V <sub>DSS</sub>	-20	V
Gate-source voltage			V <sub>GSS</sub>	-8/+6	
Drain current (DC)		(Note 1)	I <sub>D</sub>	-4	Α
Drain current (pulsed)		(Note 1,2)	I <sub>DP</sub>	-10	
Power dissipation		(Note 3)	P <sub>D</sub>	1	W
Power dissipation	(t ≤ 10 s)	(Note 3)	P <sub>D</sub>	2	W
Channel temperature			T <sub>ch</sub>	150	°C
Storage temperature			T <sub>stg</sub>	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

- Note 1: Ensure that the channel temperature does not exceed 150°C.
- Note 2: Pulse width (PW)  $\leq$  10 ms, duty  $\leq$  1%
- Note 3: Device mounted on an FR4 board.(25.4 mm × 25.4 mm × 1.6 mm, Cu Pad: 645 mm<sup>2</sup>)

Note: The MOSFETs in this device are sensitive to electrostatic discharge. When handling this device, the worktables, operators, soldering irons and other objects should be protected against anti-static discharge.

Note: The channel-to-ambient thermal resistance, R<sub>th(ch-a)</sub>, and the drain power dissipation, P<sub>D</sub>, vary according to the board material, board area, board thickness and pad area. When using this device, be sure to take heat dissipation fully into account.

#### 6. Thermal Characteristics

Characteristics		Symbol	Max	Unit
Channel-to-ambient thermal resistance	(Note 1)	R <sub>th(ch-a)</sub>	125	°C/W

Note 1: Device mounted on an 25.4 mm × 25.4 mm × 1.6 mm FR4 glass epoxy board (Cu pad: 645 mm²)



#### 7. Electrical Characteristics

## 7.1. Static Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I <sub>GSS</sub>	$V_{GS} = -8/+6 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±1	μА
Drain cut-off current		I <sub>DSS</sub>	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-1	
Drain-source breakdown voltage		V <sub>(BR)DSS</sub>	$I_D = -1 \text{ mA}, V_{GS} = 0 \text{ V}$	-20	_		V
Drain-source breakdown voltage	(Note 1)	V <sub>(BR)DSX</sub>	$I_D = -1 \text{ mA}, V_{GS} = 5 \text{ V}$	-15	_		
Gate threshold voltage	(Note 2)	$V_{th}$	$V_{DS} = -3 \text{ V}, I_{D} = -1 \text{ mA}$	-0.3	_	-1.0	
Drain-source on-resistance	(Note 3)	R <sub>DS(ON)</sub>	$I_D = -3.0 \text{ A}, V_{GS} = -4.5 \text{ V}$	_	46	55	mΩ
			$I_D = -3.0 \text{ A}, V_{GS} = -2.5 \text{ V}$	_	58	75	
			I <sub>D</sub> = -1.0 A, V <sub>GS</sub> = -1.8 V	_	70	100	
			I <sub>D</sub> = -0.5 A, V <sub>GS</sub> = -1.5 V	_	85	150	
Forward transfer admittance	(Note 3)	Y <sub>fs</sub>	$V_{DS} = -3 \text{ V}, I_{D} = -1.0 \text{ A}$	3.6	7.2		S

Note 1: If a reverse bias is applied between gate and source, this device enters  $V_{(BR)DSX}$  mode. Note that the drain-source breakdown voltage is lowered in this mode.

Note 2: Let  $V_{th}$  be the voltage applied between gate and source that causes the drain current ( $I_D$ ) to below (-1 mA for this device). Then, for normal switching operation,  $V_{GS(ON)}$  must be higher than  $V_{th}$ , and  $V_{GS(OFF)}$  must be lower than  $V_{th}$ . This relationship can be expressed as:  $V_{GS(OFF)} < V_{th} < V_{GS(ON)}$ .

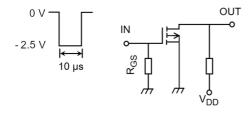
Take this into consideration when using the device.

Note 3: Pulse measurement.

#### 7.2. Dynamic Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V},$	_	630	_	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1 MHz	_	60	_	
Output capacitance	Coss		_	75	_	
Switching time (turn-on time)		$V_{DD}$ = -10 V, $I_{D}$ = -0.5 A $V_{GS}$ = 0 to -2.5 V, $R_{GS}$ = 4.7 $\Omega$ ,	_	14	_	ns
Switching time (turn-off time)		Duty $\leq$ 1%, Input: $t_r$ , $t_f$ < 5 ns Common source, See 7.3	_	68	_	

#### 7.3. Switching Time Test Circuit



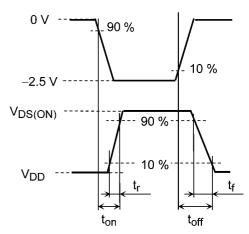


Fig. 7.3.1 Test Circuit of Switching Time

Fig. 7.3.2 Input Waveform/Output Waveform



## 7.4. Gate Charge Characteristics (Ta = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	$Q_g$	$V_{DD} = -10 \text{ V}, V_{GS} = -4.5 \text{ V},$	_	10.4	_	nC
Gate-source charge 1	Q <sub>gs1</sub>	$I_D = -3.4 \text{ A}$	_	0.7	_	
Gate-drain charge	Q <sub>gd</sub>		_	3	_	

# 7.5. Source-Drain Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Diode forward voltage	(Note 1)	V <sub>DSF</sub>	I <sub>DR</sub> = 4.0 A, V <sub>GS</sub> = 0 V	_	0.86	1.2	V

Note 1: Pulse measurement.

#### 8. Marking

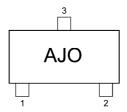


Fig. 8.1 Marking



#### 9. Characteristics Curves (Note)

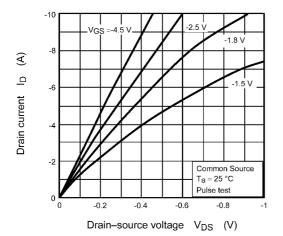


Fig. 9.1 I<sub>D</sub> - V<sub>DS</sub>

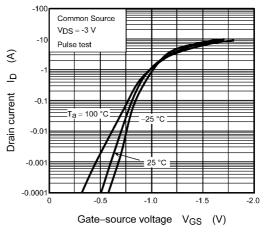


Fig. 9.2 ID - VGS

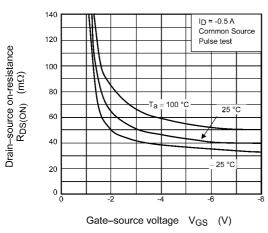


Fig. 9.3 R<sub>DS(ON)</sub> - V<sub>GS</sub>

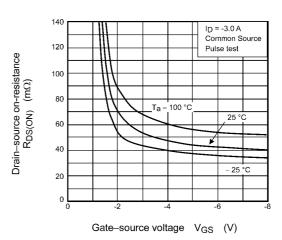


Fig. 9.4 R<sub>DS(ON)</sub> - V<sub>GS</sub>

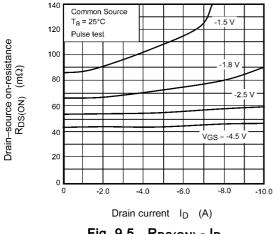


Fig. 9.5 R<sub>DS(ON)</sub> - I<sub>D</sub>

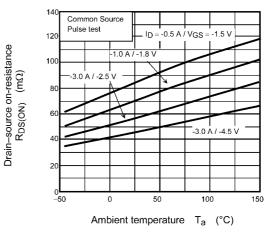
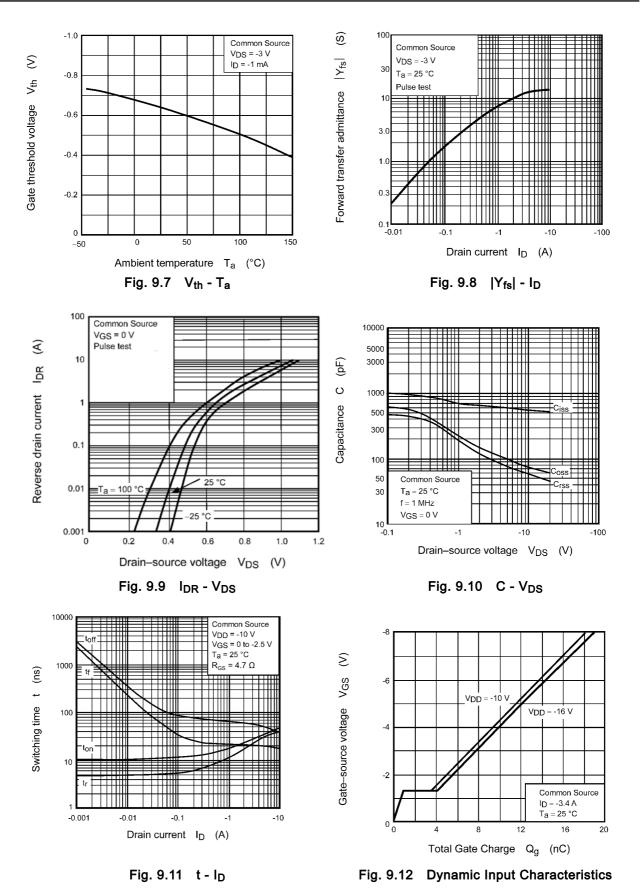


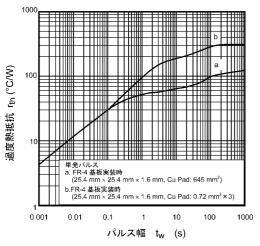
Fig. 9.6 R<sub>DS(ON)</sub> - T<sub>a</sub>

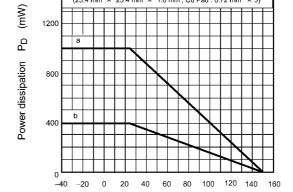
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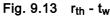




a: Mounted on an FR4 board (25.4 mm  $\times$  25.4 mm  $\times$  1.6 mm , Cu Pad : 645 mm²) b: Mounted on an FR4 board (25.4 mm  $\times$  25.4 mm  $\times$  1.6 mm , Cu Pad : 0.72 mm²  $\times$  3)

1600

Ambient temperature  $T_a$  (°C) Fig. 9.14  $P_D - T_a$ 



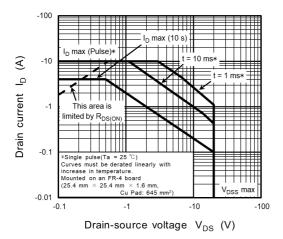


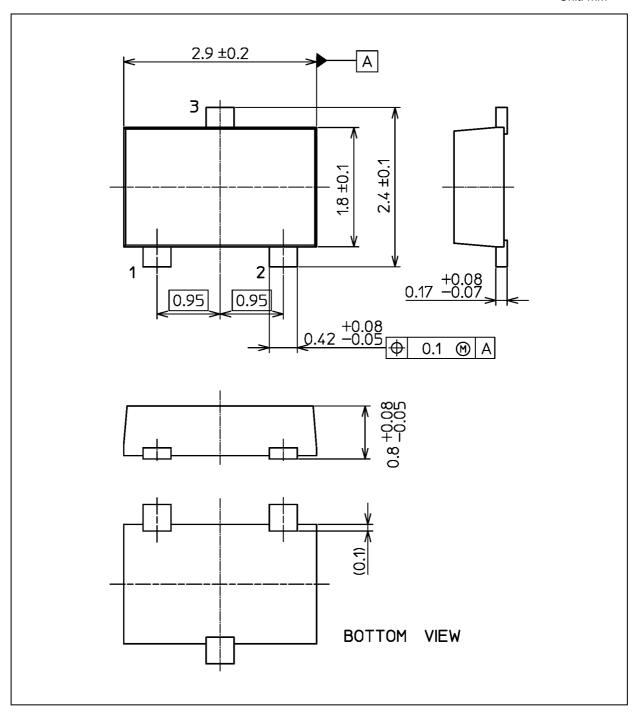
Fig. 9.15 Safe Operating Area

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



## **Package Dimensions**

Unit: mm



Weight: 0.011 g (typ.)

Package Name(s)
Nickname: SOT-23F

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